



Creative Materials, Inc.
141 Middlesex Road
Tyngsboro, MA 01879

T 978.649.4700
F 978.649.2040

121-24

ANISOTROPICALLY CONDUCTIVE, B-STAGED, EPOXY ADHESIVE FILM

DESCRIPTION: 121-24 is a B-staged, anisotropically conductive, epoxy adhesive film. This product features excellent adhesion to a variety of metallic contact pad compositions as well as other substrates. Unlike conventional conductive materials, this product is very resistant to solvents, heat, and thermocycling. Applications for 121-24 include, but are not limited to, conductive splicing of ribbon cables, PTF circuits, and electrical attachment of surface mounted devices. This product is useful in application where shorts between closely spaced contacts is a concern.

PHYSICAL DATA:

Substrate Type	Release Liner
Conductive Coating Type	Silver/polymer
Conductive Coating Thickness (mils)	3.0
Volume Resistivity (ohm-cm)	
Z- Axis:	0.001
X and Y Axis:	1×10^{12}
Solderable	No
Useful Temperature Range (°C)	-55 to 200
Lap Shear Strength (psi)	1000

Storage: Shelf Life: 12 months at -40°C (*).

* Avoid flexing film if stored at -40°C.

Safety and Handling: Use with adequate ventilation. Keep away from sparks and open flames. Avoid prolonged contact with skin and breathing of vapors.

All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either expressed or implied with respect to results or possible infringements on patents

REVISION DATE: 4/2/02 REVISION: B



CREATIVEMATERIALS

Creative Materials, Inc.
141 Middlesex Road
Tyngsboro, MA 01879

www.creativematerials.com

ISO 9001 CERTIFIED

T 978.649.4700
F 978.649.2040

PROCEDURE FOR APPLYING 121-24

1. As with all adhesive bonds, surface preparation is a vital part of the process. Carefully clean both surfaces to be bonded with MEK if possible. If MEK is not compatible with the surfaces to be bonded, another suitable solvent may be used.
2. Allow cleaned surfaces to dry completely.
3. Die cut 121-24 to the of the size of interface area, remove one of the protective liners, position and onto one of the surfaces to be bonded, and warm the substrate/adhesive to 50°C-70°C.
4. By applying slight pressure, laminate the film/adhesive to the substrate smoothing out any trapped air. Allow to cool to room temperature and peel off the other release liner.
5. Position the other substrate and apply a clamp to provide constant pressure. A pressure of 100 psi.. or higher is typically required. The amount of pressure required should be experimentally determined based on the curing temperature and geometry of the components
6. Cure for 1 hour at 150°C, or 30 minutes at 175°C.
7. Let cool to room temperature before removing pressure.

All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either expressed or implied with respect to results or possible infringements on patents

REVISION DATE: 4/2/02 REVISION: B